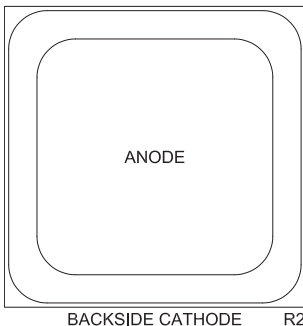


CPD07-CR6A6GPP

General Purpose Rectifier Die

6.0 Amp, 600 Volt

The CPD07-CR6A6GPP is a silicon 6.0 Amp, 600 Volt general purpose rectifier ideal for all types of industrial, consumer, medical, and power supply applications.



MECHANICAL SPECIFICATIONS:

Die Size	100 x 100 MILS
Die Thickness	8.7 MILS
Anode Bonding Pad Size	78.8 x 78.8 MILS
Top Side Metalization	Ni/Au – 4,500Å/1,350Å
Back Side Metalization	Ni/Au – 5,000Å/1,350Å
Scribe Alley Width	4.5 MILS +/- 0.6 MILS
Wafer Diameter	4 INCHES
Gross Die Per Wafer	1,056

MAXIMUM RATINGS: (T_A=25°C)

Peak Repetitive Reverse Voltage

SYMBOL

V_{RRM}

600

UNITS

V

DC Blocking Voltage

V_R

600

V

RMS Reverse Voltage

V_{R(RMS)}

420

V

Non-Repetitive Peak Reverse Voltage
(Halfwave, single phase, 60Hz peak)

V_{RSM}

720

V

Average Forward Current (T_A=60°C)

I_O

6.0

A

Peak Forward Surge Current, t_p=8.3ms

I_{FSM}

400

A

Operating and Storage Junction Temperature

T_J, T_{stg}

-65 to +150

°C

ELECTRICAL CHARACTERISTICS: (T_A=25°C unless otherwise)

SYMBOL

TEST CONDITIONS

MIN

MAX

UNITS

I_R

V_R=600V

10

μA

V_F

I_F=6.0A

1.0

V

C_J

V_R=0, f=1.0MHz

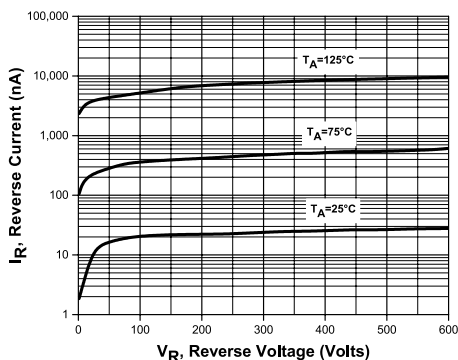
125

pF

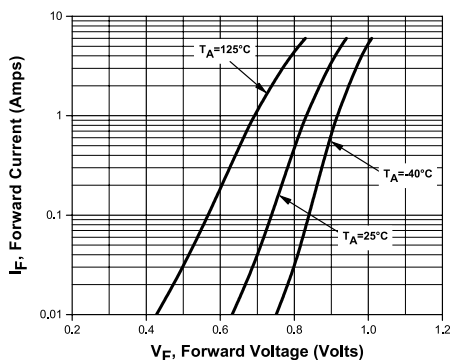
CPD07-CR6A6GPP

Typical Electrical Characteristics

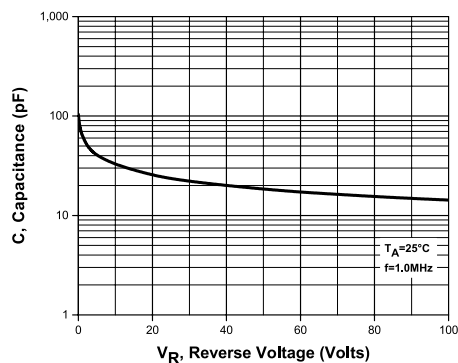
Leakage Current



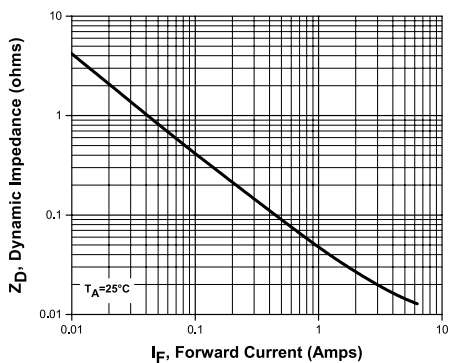
Forward Voltage



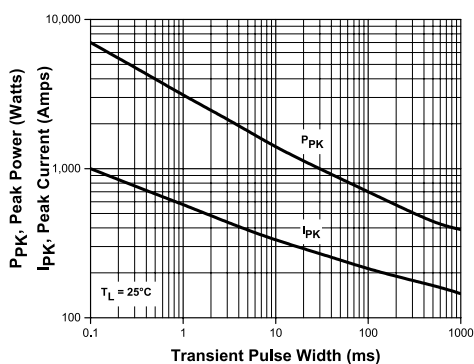
Capacitance



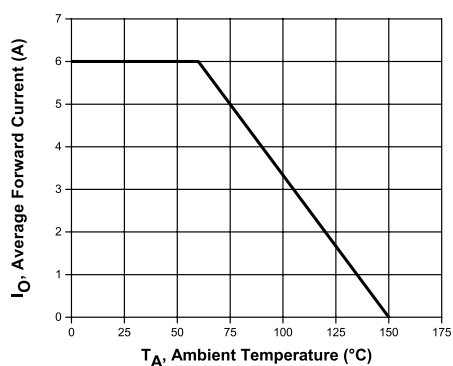
Forward Dynamic Impedance



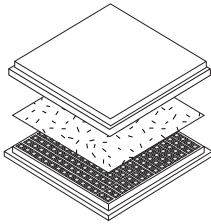
Transient Peak Power and Peak Current Capacity



Current Derating



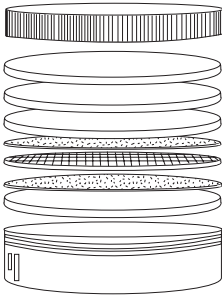
BARE DIE PACKING OPTIONS



BARE DIE IN TRAY (WAFFLE) PACK

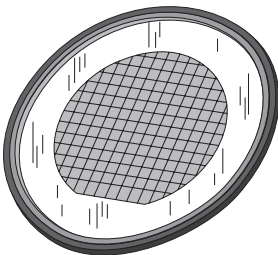
CT: Singulated die in tray (waffle) pack.
(example: CP211-PART NUMBER-CT)

CM: Singulated die in tray (waffle) pack 100% visually inspected as per MIL-STD-750, (method 2072 transistors, method 2073 diodes).
(example: CP211-PART NUMBER-CM)



UNSAWN WAFER

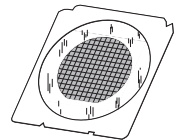
WN: Full wafer, unsawn, 100% tested with reject die inked.
(example: CP211-PART NUMBER-WN)



SAWN WAFER ON PLASTIC RING

WR: Full wafer, sawn and mounted on plastic ring,
100% tested with reject die inked.
(example: CP211-PART NUMBER-WR)

Please note: Sawn Wafer on Metal Frame (WS) is possible as a special order. Please contact your Central Sales Representative at 631-435-1110.



Visit the Central website for a complete listing of specifications:
www.centrasemi.com/bdspecs

OUTSTANDING SUPPORT AND SUPERIOR SERVICES



PRODUCT SUPPORT

Central's operations team provides the highest level of support to insure product is delivered on-time.

- Supply management (Customer portals)
- Inventory bonding
- Consolidated shipping options
- Custom bar coding for shipments
- Custom product packing

DESIGNER SUPPORT/SERVICES

Central's applications engineering team is ready to discuss your design challenges. Just ask.

- Free quick ship samples (2nd day air)
- Online technical data and parametric search
- SPICE models
- Custom electrical curves
- Environmental regulation compliance
- Customer specific screening
- Up-screening capabilities
- Special wafer diffusions
- PbSn plating options
- Package details
- Application notes
- Application and design sample kits
- Custom product and package development

REQUESTING PRODUCT PLATING

1. If requesting Tin/Lead plated devices, add the suffix "TIN/LEAD" to the part number when ordering (example: 2N2222A TIN/LEAD).
2. If requesting Lead (Pb) Free plated devices, add the suffix "PBFREE" to the part number when ordering (example: 2N2222A PBFREE).

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